



- L4: (6786) ['257/684,690,707,737,778,668,666'].CCLS.
- L5: (0) ["4 and "tape carrier package""],PN.
- L6: (95) 4 and "tape carrier package"
- L8: (0) 7 and leadframe
- L9: (408) 4 and leadframe
- L10: (0) 9 and "tape carrier package"
- L7: (34) 6 and "Tape automated bonding"
- L11: (308) 4 and [col or loc]
- L12: (2) 11 and "tape carrier package"

### Failed

- [0].if [col or chip-on-lead] and semiconductor and [f"polyimide"]

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DBs: USPAT;US;PGPUB;EPO;JPO;DERWENT;IBM TDB

Plurals

Synonyms

Default operator: OR

Highlight all hit terms initially

11 and "tape carrier package"

BRS form

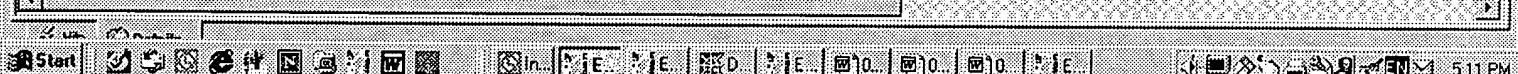
IS&R form

Image

Text

U	I	Document ID	Iss	Page	Title	Current OR	Current XRef	Retrieval Classif	Inve
1	<input type="checkbox"/>	<input type="checkbox"/> US 20010002066 A1		42	Semiconductor device, lead-patterning substrate, and electronics device,				Mita, Mamoru , Murakami, Gen
2	<input type="checkbox"/>	<input type="checkbox"/> US 5894107 A	199:11 904: 13		Chip-size package [CSP] using a multi-layer laminated lead frame	174/52.2	174/52.4 ; 257/676 ; 257/693		Lee, Kyu Jin , et al.

LOC



U	I	Document ID	Iss	Page	Title	Current OF	Current XRef	Retrieval Classif	In
1	<input type="checkbox"/>	US 20010026010 A1		52	Semiconductor device and process of production of same				Horiuchi, Michi, Kurihara, Tak, et al.
2	<input checked="" type="checkbox"/>	US 20010026009 A1		45	Semiconductor device, a semiconductor module loaded with said				Tsunesa, Kens, Sugano, Tosh, et al.
3	<input checked="" type="checkbox"/>	US 20010026008 A1		45	Semiconductor device, a semiconductor module loaded with said				Tsuneda, Kens, Sugano, Tosh, et al.
4	<input checked="" type="checkbox"/>	US 20010012643 A1		28	Package having very thin semiconductor chip, multichip module assembled by				Asada, Junichi
5	<input checked="" type="checkbox"/>	US 6239496 B1	200 105 29	27	Package having very thin semiconductor chip, multichip module assembled by	257/777	257/685 ; 257/686 ; 257/698		Asada, Junichi
6	<input checked="" type="checkbox"/>	US 6125042 A	200 009 26	10	Ball grid array semiconductor package having improved EMI characteristics	361/760	257/737 ; 257/738 ; 257/779		Verdi, Fred W, et al.
7	<input checked="" type="checkbox"/>	US 6114754 A	200 009 05	19	Tape automated bonding film	257/668	257/673 ; 257/778		Kata, Keiichiro
8	<input checked="" type="checkbox"/>	US 5895969 A	199 904 20	16	Thin type semiconductor device, module structure using the device and	257/696	257/676		Masuda, Masa, et al.
9	<input checked="" type="checkbox"/>	US 5894107 A	199 904 13	11	Chip-size package [CSP] using a multi-layer laminated lead frame	174/52.2	174/52.4 ; 257/676 ; 257/693		Lee, Kyu Jin, et al.
10	<input checked="" type="checkbox"/>	US 5821614 A	199 810 13	30	Card type semiconductor device	257/679	235/492 ; 257/712 ; 257/713		Hashimoto, No, et al.
11	<input checked="" type="checkbox"/>	US 5818105 A	199 810 06	16	Semiconductor device with plastic material covering a semiconductor chip	257/696	257/695 ; 257/701 ; 257/703		Kouda, Tsunen
12	<input checked="" type="checkbox"/>	US 5723903 A	199 14	14	Thin type semiconductor device, module	257/696	257/676		Masuda, Masa

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Active

1.1. (241) "tape carrier package" and "tape automated bonding"

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U	I	Document ID	Iss	Page	Title	Current OR	Current XRef	Retrieval Classif	In
6	<input checked="" type="checkbox"/>	US 6125042 A	200 009	10 26	Ball grid array semiconductor package having improved EMI characteristics	361/760	257/737 ; 257/738 ; 257/779		Verdi, Fred W., et al.
7	<input checked="" type="checkbox"/>	US 6114754 A	200 009	19 05	Tape automated bonding film	257/668	257/673 ; 257/778		Kata, Keiichiro
8	<input checked="" type="checkbox"/>	US 5895969 A	199 904	16 20	Thin type semiconductor device, module structure using the device and	257/696	257/676		Masuda, Masa, et al.
9	<input checked="" type="checkbox"/>	US 5894107 A	199 904	11 13	Chip-size package (CSP) using a multi-layer laminated lead frame	174/52.2	174/52.4 ; 257/676 ; 257/693		Lee, Kyu Jin, et al.
10	<input checked="" type="checkbox"/>	US 5821614 A	199 810	30 13	Card type semiconductor device	257/679	235/492 ; 257/712 ; 257/713		Hashimoto, No, et al.
11	<input checked="" type="checkbox"/>	US 5818105 A	199 810	16 06	Semiconductor device with plastic material covering a semiconductor chip	257/696	257/695 ; 257/701 ; 257/703		Kouda, Tsunen
12	<input checked="" type="checkbox"/>	US 5723903 A	199 803	14 03	Thin type semiconductor device, module structure using the device and	257/696	257/676 ; 257/686 ; 257/787		Masuda, Masa, et al.
13	<input checked="" type="checkbox"/>	US 5586270 A	199 612	21 17	Method and apparatus for upgrading a central processing unit and	710/301	710/13 ; 711/130		Rotier, Michael, et al.
14	<input checked="" type="checkbox"/>	US 5446313 A	199 508	13 29	Thin type semiconductor device and module structure using the device	257/666	257/686 ; 257/702 ; 257/787		Masuda, Masa, et al.
15	<input checked="" type="checkbox"/>	US 5410182 A	199 504	9 25	High density semiconductor device having inclined chip mounting	257/692	257/775 ; 257/776		Kurafuchi, Kazu, et al.
16	<input checked="" type="checkbox"/>	US 5349236 A	199 409	17 20	Reusable fixture for carrier tape	257/701	206/713 ; 257/668 ; 257/727		Oshino, Fumio, et al.

L Number	Hits	Search Text	DB	Time stamp
-	241	"tape carrier package" and "tape automated bonding"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:45
-	184	("tape carrier package" and "tape automated bonding") and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:46
-	16	(("tape carrier package" and "tape automated bonding") and semiconductor) and (thin near3 package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:55
-	6786	("257/684,690,707,737,778,668,666").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:56
-	0	("4 and "tape carrier package").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:57
-	95	(("257/684,690,707,737,778,668,666").CCLS.) and "tape carrier package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:57
-	0	((("257/684,690,707,737,778,668,666").CCLS.) and "tape carrier package") and "Tape automated bonding" and leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:58
-	408	((("257/684,690,707,737,778,668,666").CCLS.) and leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:58
-	0	((("257/684,690,707,737,778,668,666").CCLS.) and leadframe) and "tape carrier package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:58
-	34	((("257/684,690,707,737,778,668,666").CCLS.) and "tape carrier package") and "Tape automated bonding"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:08
-	308	((("257/684,690,707,737,778,668,666").CCLS.) and (col or loc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:09
-	2	((("257/684,690,707,737,778,668,666").CCLS.) and (col or loc)) and "tape carrier package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:11

	33	(("257/684,690,707,737,778,668,666").CCLS.) and ("chip\$on\$lead" or chip-on-lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:12
	0	((("257/684,690,707,737,778,668,666").CCLS.) and ("chip\$on\$lead" or chip-on-lead)) and "tape carrier package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:13
	17	((("257/684,690,707,737,778,668,666").CCLS.) and ("chip\$on\$lead" or chip-on-lead)) and "thin package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:13